

Octal Buffer/Line Drivers, 3-State

CD74AC/ACT540 - Inverting CD74AC/ACT541 - Non-Inverting

Type Features:

- Buffered inputs
- Typical propagation delay: 4.5 ns @ Vcc = 5 V, TA = 25°C, CL = 50 pF

The CD54/74AC540, -541, and CD54/74ACT540, -541 octal buffer/line drivers use the RCA ADVANCED CMOS technology. The CD54/74AC/ACT540 are inverting 3-state buffers having two active-LOW output enables. The CD54/74AC/ACT541 are non-inverting 3-state buffers having two active-LOW output enables.

The CD74AC540, -541, and CD74ACT540, -541 are supplied in 20-lead dual-in-line plastic packages (E suffix) and in 20-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Industrial (-40 to +85°C) and Extended Industrial/Military (-55 to +125°C).

The CD54AC540, -541, and CD54ACT540, -541, available in chip form (H suffix), are operable over the -55 to +125°C temperature range.

Family Features:

- Exceeds 2-kV ESD Protection MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST®/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply.
- ± 24-mA output drive current
 - Fanout to 15 FAST® ICs
 - Drives 50-ohm transmission lines

TRUTH TABLE

	CD54/74AC/ACT540							
INPUTS		OUTPUTS						
OE1, OE2	Α	Υ						
L	L	Н						
L	н	L						
н	Х	. Z						

TRUTH TABLE

CD54/74AC/ACT541						
INPUTS OUTPUTS						
OE1, OE2	A	Υ				
L	L	L				
L	н	Н				
н	x	Z				

H = High Voltage L = Low Voltage

X = Immaterial

Z = High Impedance

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MAXIMUM RATINGS, Absolute-Maximum Values:	
DC SUPPLY-VOLTAGE (V _{CC})	0.5 to 6 V
DC INPUT DIODE CURRENT, $I_{ K }$ (for $V_{ } < -0.5$ or $V_{ } > V_{CC} + 0.5$ V)	±20 mA
DC OUTPUT DIODE CURRENT, I_{OK} (for $V_O < -0.5$ or $V_O > V_{CC} + 0.5$ V)	±50 mA
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, IO (for VO > -0.5 or VO < VCC + 0.5 V)	±50 mA
DC V _{CC} OR GROUND CURRENT (I _{CC} or I _{GND})	±100 mA*
PACKAGE THERMAL IMPEDANCE, θJA (see Note 1): E package	69°C/W
M package	58°C/W
STORAGE TEMPERATURE (T _{stq})	–65 to +150°C
LEAD TEMPERATURE (DURINĞ SOLDERING):	
At distance 1/16 \pm 1/32 in. (1.59 \pm 0.79 mm) from case for 10 s maximum	+265°C
Unit inserted into PC board min. thickness 1/16 in. (1.59 mm) with solder contacting lead tips only	+300°C
* For up to 4 outputs per device: add ±25 mA for each additional output	

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERICTIC	LIM	LIMITS		
CHARACTERISTIC	MIN.	MAX.	UNITS	
Supply-Voltage Range, V _{cc} *: (For T _A = Full Package-Temperature Range) AC Types ACT Types	1.5 4.5	5.5 5.5	V	
DC Input or Output Voltage, V _I , V _O	0	Vcc	V	
Operating Temperature, T _A :	-55	+125	°C	
Input Rise and Fall Slew Rate, dt/dv at 1.5 V to 3 V (AC Types) at 3.6 V to 5.5 V (AC Types) at 4.5 V to 5.5 V (ACT Types)	0 0 0	50 20 10	ns/V ns/V ns/V	

^{*}Unless otherwise specified, all voltages are referenced to ground.

TERMINAL ASSIGNMENT DIAGRAMS



NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

Technical Data _	
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STATIC ELECTRICAL CHARACTERISTICS: AC Series

					AMBIENT TEMPERATURE (TA) - °C						
CHARACTERISTI	cs	TEST CO	NDITIONS	V _{cc}	+:	25	-40 to	o +85	-55 to	+125	UNITS
		V, (V)	l _o (mA)	(v)	MIN.	MAX.	MIN.	MAX.	MIN. MAX.		
High-Level Input				1.5	1.2	_	1.2		1.2		
Voltage	ViH			3	2.1	_	2.1		2.1		V
				5.5	3.85	_	3.85	_	3.85		
Low-Level Input				1.5	_	0.3	_	0.3		0.3	
Voltage	VIL		,	3		0.9	_	0.9		0.9	_ v
			Ì	5.5	-	1.65	_	1.65		1.65	
High-Level Output			-0.05	1.5	1.4		1.4	_	1.4	_	
Voltage	V_{OH}	V _{IH}	-0.05	- 3	2.9		2.9		2.9		
		or	-0.05	4.5	4.4	_	. 4.4	_	4.4	_	1
		VIL	-4	3	2.58	_	2.48		2.4	_] v
			-24	4.5	3.94	_	3.8	_	3.7	-]
		#, * {	-75	5.5			3.85]
		" , " }	-50	5.5			_		3.85	_]
Low-Level Output			0.05	1.5		0.1	_	0.1	_	0.1	
Voltage	Vol	VIH	0.05	3	_	0.1	_	0.1	_	0.1	1
		or	0.05	4.5		0.1		0.1	_	0.1]
		V _{IL}	12	3	_	0.36	_	0.44	_	0.5	٧
			24	4.5	_	0.36	_	0.44		0.5]
		#, * {	75	5.5	_	_	_	1.65	_	_]
		", ^ }	50	5.5		_	_	_	_	1.65]
Input Leakage Current	l ₁	V _{cc} or GND		5.5	-	±0.1	_	±1	_	±1	μΑ
3-State Leakage		ViH									
Current	loz	or	ļ				1				
		VıL		-			}				
		Vo=		5.5	_	±0.5	_	±5		±10	μΑ
		Vcc	Ì]						
		or			ļ			1	1	1	[
		GND	1		1					L	Ì
Quiescent Supply Current, MSI	Icc	V _{cc} or GND	0	5.5	_	8	_	80	_	160	μΑ

[#]Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize

power dissipation.

* Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

					AMBIENT TEMPERATURE (TA) - °C]						
CHARACTERISTICS		TEST CONDITIONS		V _{cc} +25 -40 to +85 -5		V _{CC} +25 -40 to +85		V _{CC} +25 -40 to +85 -55		V _{cc} +25 -40 to +85 -55		V _{CC} +25 -40 to +85 -55 to +1		+25 -40 to +85		+125	UNITS
		V, (V)	I _o (mA)	(V)	MIN. MAX.		MIN.	MAX.	MIN.	MAX.]						
High-Level Input Voltage	ViH			4.5 to 5.5	2	_	2	_	2	_	v						
Low-Level Input Voltage	VIL			4.5 to 5.5		0.8		0.8	_	0.8	v						
High-Level Output		ViH	-0.05	4.5	4.4	_	4.4		4.4								
Voltage	V _{OH}	or V _{IL}	-24	4.5	3.94		3.8		3.7		v						
		#, * {	-75	5.5	_		3.85		_] .						
		"	-50	5.5		_	_		3.85	_							
Low-Level Output		ViH	0.05	4.5	_	0.1		0.1		0.1							
Voltage	Vol	or V _{IL}	24	4.5		0.36		0.44	_	0.5] v [
		#. * }	75	5.5			_	1.65] `						
		··· \	50	5.5						1.65							
Input Leakage Current	l,	V _{CC} or GND		5.5	_	±0.1	_	±1		±1	μА						
3-State Leakage Current	loz	VIH or VIL Vo = Vcc or GND		5.5	_	±0.5		±5	_	±10	μΑ						
Quiescent Supply Current, MSI	lcc	V _{cc} or GND	0	5.5	_	8	_	80		160	μΑ						
Additional Quiescent Current per Input P TTL Inputs High 1 Unit Load		V _{cc} -2.1		4.5 to 5.5		2.4		2.8		3	mA						

[#]Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

* Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT	LOAD*
	540	541
DATA	1.42	0.5
OE1, OE2	1.3	1.3

^{*}Unit load is Δl_{CC} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25° C.

SWITCHING CHARACTERISTICS: AC Series; t,, t, = 3 ns, C, = 50 pF

			AMBI	T			
CHARACTERISTICS	SYMBOL	(V)	-40 1	lo +85	-55 to +125		UNITS
			MIN.	MAX.	MIN.	MAX.	7
Propagation Delays: Data to Output AC540	tpLH tpHL	1.5 3.3* 5†	2.4 1.8	77 8.6 6.2	2.4 1.7	85 9.5 6.8	ns
AC541	t _{PLH} t _{PHL}	1.5 3.3 5	 2.8 2.1	89 9.9 7.1	2.7 2	98 10.9 7.8	ns
Enable, to Output to Output	t _{PZL} t _{PZH}	1.5 3.3 5	4.6 3.1	136 16.4 10.9	- 4.5 3	150 18 12	ns
Disable to Output to Output	t _{PLZ} t _{PHZ}	1.5 3.3 5	3.9 3.1	136 13.6 10.9	- 3.8 3	150 15 12	ns
Power Dissipation Capacitance AC540 AC541	C _{PD} ‡	<u> </u>	60 Typ. 60 Typ. 60 Typ. 60 Typ.			pF	
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{онv} See Fig. 1	5	4 Typ. @ 25°C		٧		
Max. (Peak) Vol. During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5	1 Typ. @ 25°C			V	
Input Capacitance	Cı	_	_	10	_	10	pF
3-State Output Capacitance	Co	_	<u> </u>	15	_	15	pF

SWITCHING CHARACTERISTICS: ACT Series; t,, t, = 3 ns, C, = 50 pF

-			AMBI				
CHARACTERISTICS	SYMBOL	V _{cc} (V)	-40	-40 to +85		-55 to =125	
			MIN.	MAX.	MIN.	MAX.]
Propagation Delays: Data to Output ACT540	t _{PLH} t _{PHL}	5†	1.9	6.5	1.8	7.2	ns
ACT541	t _{PLH} t _{PHL}	5†	2.1	7.5	2.1	8.2	ns
Enable to Output	t _{PZL} t _{PZH}	5	3.5	12.2	3.4	13.4	ns
Disable to Output	t _{PLZ} t _{PHZ}	5	3.5	12.2	3.4	13.4	ns
Power Dissipation Capacitance ACT540 ACT541	C _{PO} §	-		Тур. Тур.	60 Typ. 60 Typ.		pF
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{онv} See Fig. 1	5	4 Typ. @ 25°C			V	
Max. (Peak) Vol. During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5	1 Typ. @ 25°C		v		
Input Capacitance	Cı	_	_	10	_	10	ρF
3-State Output Capacitance	Co	_		15	_	15	pF

*3.3 V: min. is @ 3.6 V max. is @ 3 V

§C_{PD} is used to determine the dynamic power consumption, per channel.

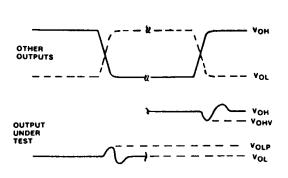
For AC series, $P_D = V_{cc}^2 f_i (C_{PD} + C_L)$ For ACT series, $P_D = V_{cc}^2 f_i (C_{PD} + C_L) + V_{cc} \Delta I_{cc}$ where

 $f_i = input frequency$ C_L = output load capacitance

 V_{CC} = supply voltage.

†5 V: min. is @ 5.5 V max. is @ 4.5 V

PARAMETER MEASUREMENT INFORMATION



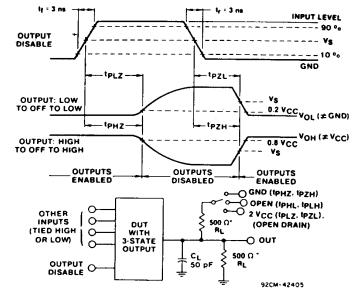
NOTES:

- 1. VOHY AND VOLP ARE MEASURED WITH RESPECT TO A GROUND REFERENCE NEAR THE OUTPUT UNDER TEST.

 2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS:
- PRR ≤ 1 MHz, t₇ = 3 ns, t₁ = 3 ns, SKEW 1 ns.

 3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED.
 IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH 0.1 pF CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

9205-42406



*FOR AC SERIES ONLY: WHEN v_{CC} = 1.5 V, r_L = 1 $k\Omega$

Fig. 1 - Simultaneous switching transient waveforms.

Fig. 2 - Three-state propagation delay waveforms and test circuit.

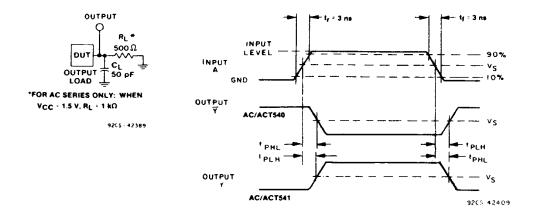


Fig. 3 - Propagation delay times and test circuit.

	CD54/74AC	CD54/74ACT
Input Level	V _{cc}	3 V
Input Switching Vottage, Vs	0.5 V _{cc}	1.5 V
Output Switching Voltage, V ₅	0.5 V _{cc}	0.5 V _{cc}

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